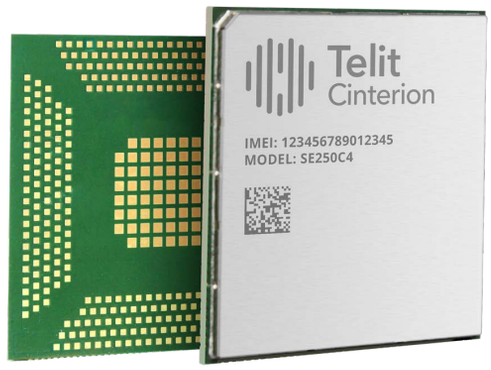
SE250C4

LTE Cat 4 150/50
Wi-Fi 802.11 a/b/g/n/ac
Bluetooth® Low Energy 5.0



Product Description

The SE250C4 is Telit Cinterion's third generation of smart modules with Android and Linux that supports LTE Cat 4, Wi-Fi and Bluetooth® connectivity, and an embedded GNSS receiver in one package.

Powered by the Qualcomm® Dragonwing™ Q-2390 quad-core ARM CPUs (1 Gold A78 and 3 Silver A55) with built-in Adreno™ 704 GPU, the SE250C4 module is ideal for industrial and consumer applications requiring high data rates, multimedia functions and edge computing capabilities.

It provides interfaces to easily connect to displays, cameras and various sensors and come with high-performance application processing and graphical processing power to boost the next generation of smart IoT devices requiring multimedia capabilities. Android allows easy, flexible and streamlined application development and opens access to the biggest software ecosystem for enhanced innovation. It also supports Linux (Yocto)*.

A rich set of interfaces, including but not limited to LCM, camera, touch screen, microphone, headset, speaker, SDIO 3.0, USB 3.1, USB 2.0, PCIe, 2×RGMII, UART, SPI and I2C, make these modules perfect for a wide range of IoT applications. These use cases include:

- Mobile point-of-sale (mPOS), smart cash registers and vending machines
- Smart alarm panels
- Security surveillance cameras and home automation security systems
- Smart home gateways
- Smart robots
- Industrial personal digital assistants (PDA)
- Handled PCs and tablets
- Police and law enforcement equipment
- Telematics cameras
- Digital video recorders (DVR)
- In-car video streaming and entertainment systems

SE250C4 delivers maximum data rates of up to 150 Mbps downlink and 50 Mbps uplink over the LTE network and support Wi-Fi communication in compliance with IEEE 802.11a/b/g/n/ac standards and Bluetooth® Low Energy 5.0.

It also embeds a multi-constellation and high-sensitivity GNSS (GPS, BeiDou, GLONASS and Galileo) receiver for precise positioning. The compact LGA 41 x 43 mm form factor allows easy integration in portable devices. With the functionality and integrated resources in these compact modules, developers can easily and quickly develop user-friendly, touch-screen-equipped, IoT-enabled devices. SE250C4 integrates a 1.1 INT8 TOPS NPU for AI workloads and an MCU running Zephyr OS for real-time control applications.

Key Benefits

- Pre-certified processing power, rich multimedia experience and reliable wireless connectivity in one package for fast time to market
- Android, for easy application development, and Linux*
- Exceptional application and system performance based on Qualcomm® Dragonwing™ Q-2390-core ARM CPUs: 1 × Gold A78 @ 1.9 GHz + 3 × Silver A55 @ 1.8 GHz
- Enhanced mobile rendering APIs for image and video applications via Adreno 704
- Dual Cameras 25MP (13+13 MP)
- Supports recording and playback of 1080p video at 30 FPS
- Multi-mode 4G/3G/2G cellular radio for wide-area network coverage
- Wi-Fi and Bluetooth® connectivity for short-range communications
- Onboard multi-constellation GNSS positioning receiver

Variants

The SE250C4 includes two variants:

- The SE250C4-EU for Europe and other regions includes support for Band 28 and fallback to legacy 3G and 2G technologies
- The SE250C4-WE: World-wide, Wi-Fi only (non Cellular)

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AVAILABLE FOR

Europe

World Wide (non cellular)

SE250C4

	SE250C4-EU	SE250C4-WE
Market	EU, China and other regions	World-wide, Wi-Fi only (non-cellular)
LTE-FDD	1, 3, 5, 7, 8, 20, 28	-
LTE-TDD	38, 40, 41	-
WCDMA	1, 5, 8	-
GSM/GPRS/Edge	3, 8	-

Product Features

- LTE-FDD Cat 4
- Rx diversity and MIMO DL 2 x 2
- Single Rx option
- Wi-Fi IEEE 802.11a/b/g/n/ac
- Bluetooth® Low Energy 5.0
- Simultaneous support of GPS, GLONASS, BeiDou and Galileo
- Android 16 full 64 bit
- Linux (Yocto)*
- No VoLTE support

Hardware and Electrical Specifications

- Dimensions: 41 x 43mm
- LGA 408 pads + 60 thermal pads
- USB 3.1, USB 2.0
- NPU 1.1 INT8 TOPS
- MCU
- PCIe Gen2 1L
- 2×RGMII (TSN)
- UART
- SPI
- I2C
- LCM
- Camera 2x4-lane CSI
- Touch screen
- Microphone
- Headset
- Speaker
- SDIO 3.0
- Battery charge management
- GPIOs
- RTC
- 2x 1.8 V/3 V SIM (UIM) interfaces with dual-SIM dual-standby (DSDS) support
- Cellular main antenna and Rx diversity antenna pads, GNSS antenna pad
- Temperature range*: -30°C to+75° C
- REACH* and RoHS* compliant
- Output power
  - Class 3 (0.2 W, 23 dBm) @ LTE
- Supply voltage range:
  - Nominal: 3.8 V dc
  - Range: 3.5-4.4 V dc

Data Throughput

LTE Cat 4

- Uplink up to 50 Mbps (FDD) and 30 Mbps (TDD)
- Downlink up to 150 Mbps (FDD) and 130 Mbps (TDD)

Approvals*

- RED, GCF, RoHS, REACH, BT-SIG, WFA (SE250C4-EU)
- BT-SIG, WFA (SE250C4-WE)

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